
**Polprevodniški elementi - Mehanske in klimatske preskusne metode - 27. del:
Preskušanje občutljivosti na elektrostatične izpraznitve (ESD) - Model stroja
(MM) (IEC 60749-27:2006)**

(istoveten EN 60749-27:2006)

Semiconductor devices - Mechanical and climatic test methods - Part 27:
Electrostatic discharge (ESD) sensitivity testing - Machine model (MM) (IEC 60749-
27:2006)

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English version

**Semiconductor devices -
Mechanical and climatic test methods
Part 27: Electrostatic discharge (ESD) sensitivity testing -
Machine model (MM)
(IEC 60749-27:2006)**

Dispositifs à semiconducteurs -
Méthodes d'essais mécaniques
et climatiques
Partie 27: Essai de sensibilité aux
décharges électrostatiques (DES) -
Modèle de machine (MM)
(CEI 60749-27:2006)

Halbleiterbauelemente -
Mechanische und klimatische
Prüfverfahren
Teil 27: Prüfung der Empfindlichkeit
gegen elektrostatische Entladungen
(ESD) -
Machine Model (MM)
(IEC 60749-27:2006)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47/1861/FDIS, future edition 2 of IEC 60749-27, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60749-27 on 2006-08-01.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2007-05-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2009-08-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60749-27:2006 was approved by CENELEC as a European Standard without any modification.

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Annex ZA
(normative)

**Normative references to international publications
with their corresponding European publications**

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61340-3-2	- ¹⁾	Electrostatics Part 3-2: Methods for simulation of electrostatic effects - Machine model (MM) - Component testing	EN 61340-3-2	2002 ²⁾
IEC 60749-26	- ¹⁾	Semiconductor devices - Mechanical and climatic test methods Part 26: Electrostatic discharge (ESD) sensitivity testing - Human body model (HBM)	EN 60749-26	2006 ²⁾

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¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

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**Dispositifs à semiconducteurs –
Méthodes d'essais mécaniques
et climatiques –**

Partie 27:

**Essai de sensibilité aux décharges
électrostatiques (DES) –
Modèle de machine (MM)**

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**Semiconductor devices –
Mechanical and climatic test methods –**

Part 27:

**Electrostatic discharge (ESD) sensitivity
testing –
Machine model (MM)**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –****Part 27: Electrostatic discharge (ESD) sensitivity testing –
Machine model (MM)**

FOREWORD

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International Standard IEC 60749-27 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition, published in 2003, and has been revised in collaboration with technical committee 101. Whilst it does not contain any major technical changes, reference is now made, where necessary, to IEC 61340-3-2.